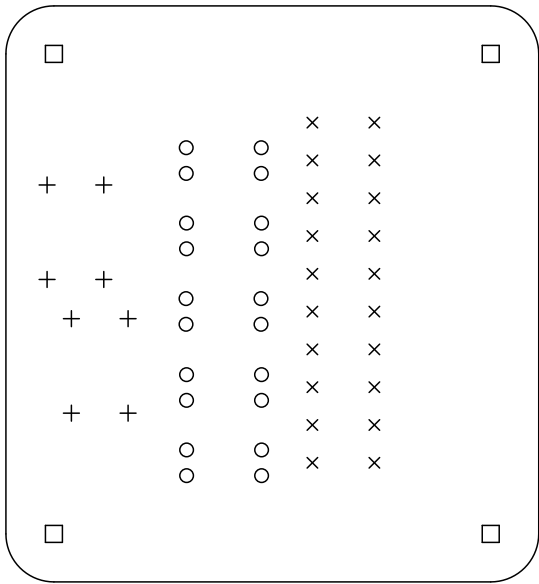


[illegible]

Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent	
A	F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
	F.Paste	Top Solder Paste		0 mils		1	0
	F.Mask	Top Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
	F.Cu	copper		1.37795 mils		1	0
	Dielectric	core	FR4	59.44882 mils	Not specified	4.5	0.02
	B.Cu	copper		1.37795 mils		1	0
	B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
	B.Paste	Bottom Solder Paste		0 mils		1	0
	B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0

BOARD CHARACTERISTICS

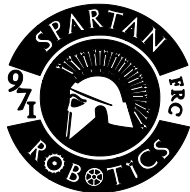
Copper Layer Count:	2	Board Thickness:	1.6000 mm
Board overall dimensions:	70.4850 mm x 76.2000 mm		
Min track/spacing:	0.0000 mm / 0.0000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		



Drill Map:

×	1.397mm	/	0.0550"	(20 holes)
○	1.800mm	/	0.0709"	(20 holes)
+	2.108mm	/	0.0830"	(8 holes)
□	3.175mm	/	0.1250"	(4 holes) (not plated)

NOTES	LAYERS
1.Layers: 2 2.Thickness: 1.6 3.Surface finish: HASL 4.Outer Copper Weight: 2oz 5.Via covering: Tented 6.Min hole size: .3mm 7.Gold Fingers: No 8.Castellated Holes: No 9.Edge Plating: No	User.1 Edge.Cuts



Spartan Robotics

Sheet:
 File: PowerDistribution.kicad_pcb
Title: Power Distribution Board
 Size: B Date: 2024-10-12 Rev: R2
 KiCad E.D.A. 8.0.5 Page: 1/1